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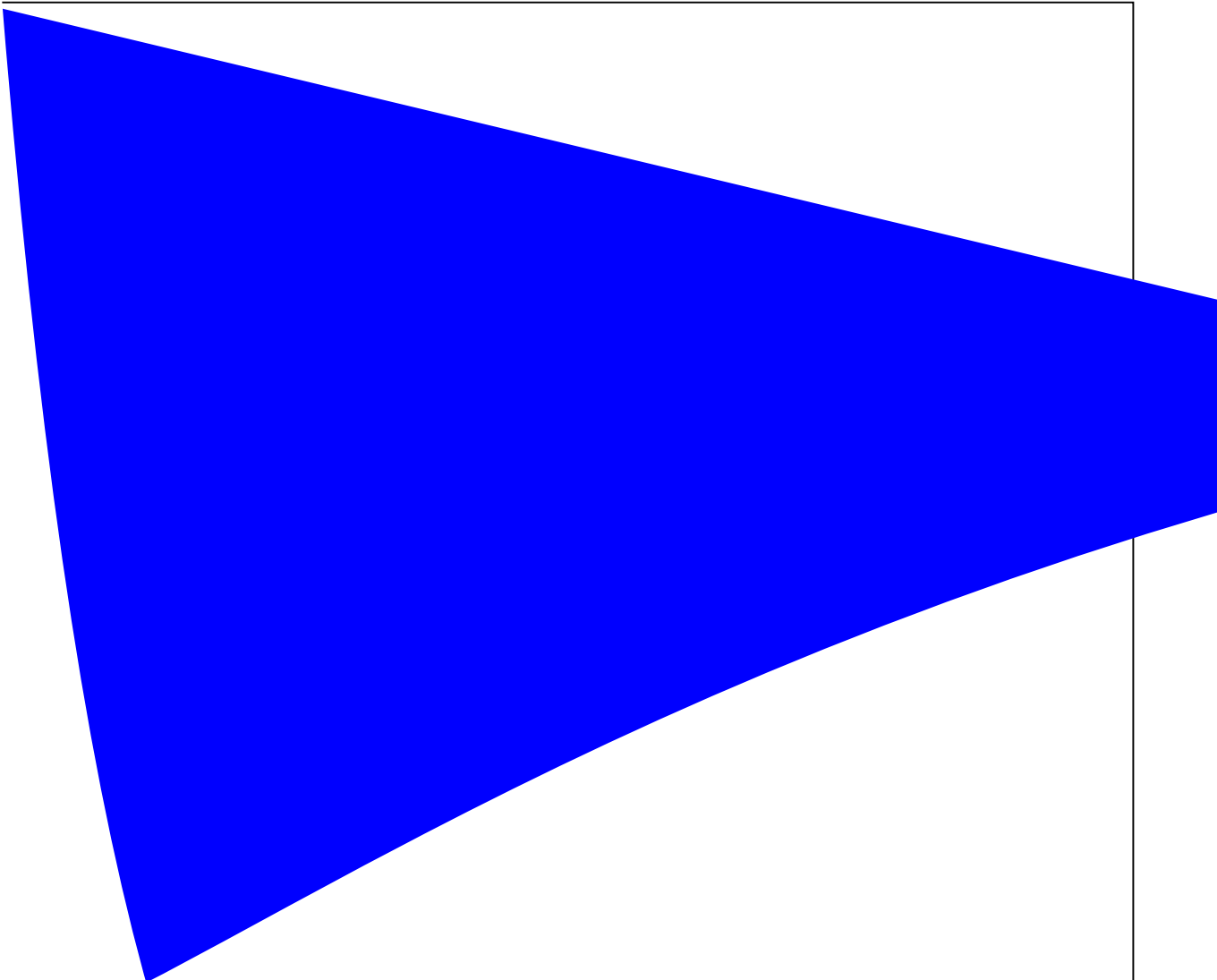


Photo Transistor Diode Specification

●Commodity: Photo Transistor

●Ic(on) Bin Code ($V_{CE}=5V$, $E_e=1mW/cm^2$, $\lambda=940nm$)

| BIN CODE | Min. (mA) | Max. (mA) |
|----------|-----------|-----------|
| X2 | 3.7 | 4.4 |
| X3 | 4.4 | 5.3 |



LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures (Fig.1).

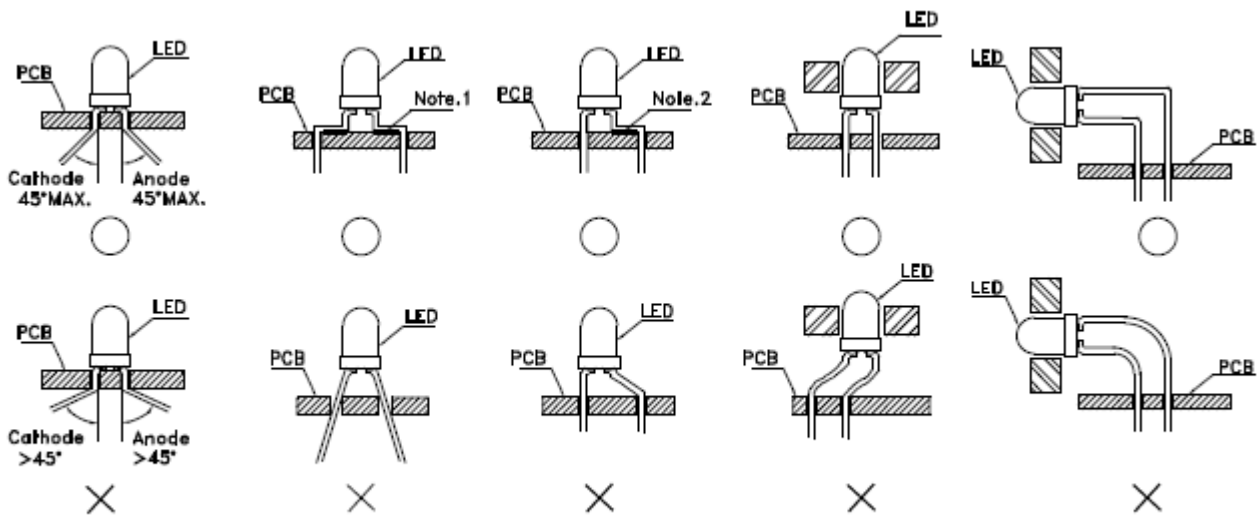


Fig. 1

Note 1-2: Do not route PCB trace in the contact area between the lead frame and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit (Fig.2).

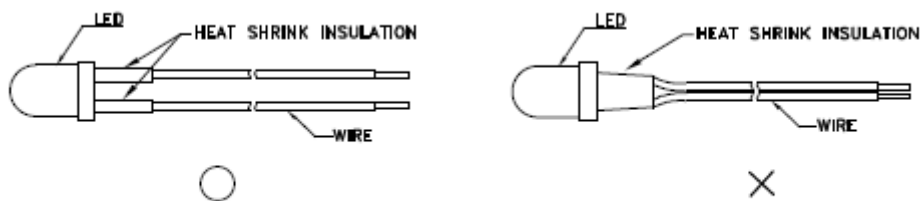


Fig. 2

3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

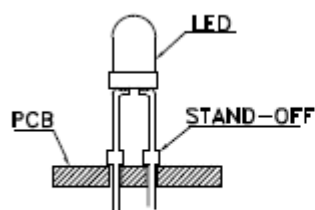


Fig. 3

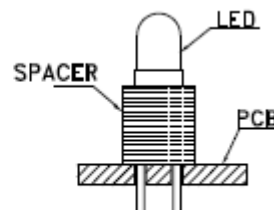
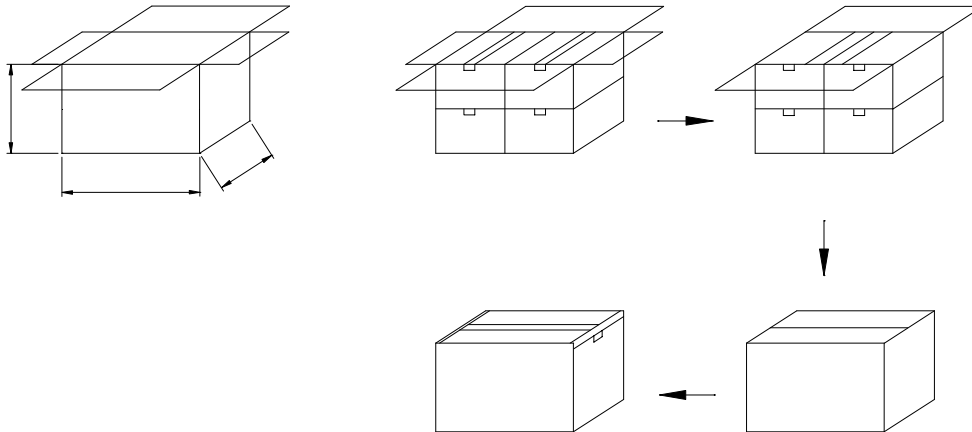
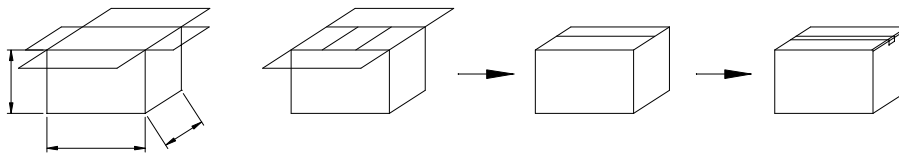
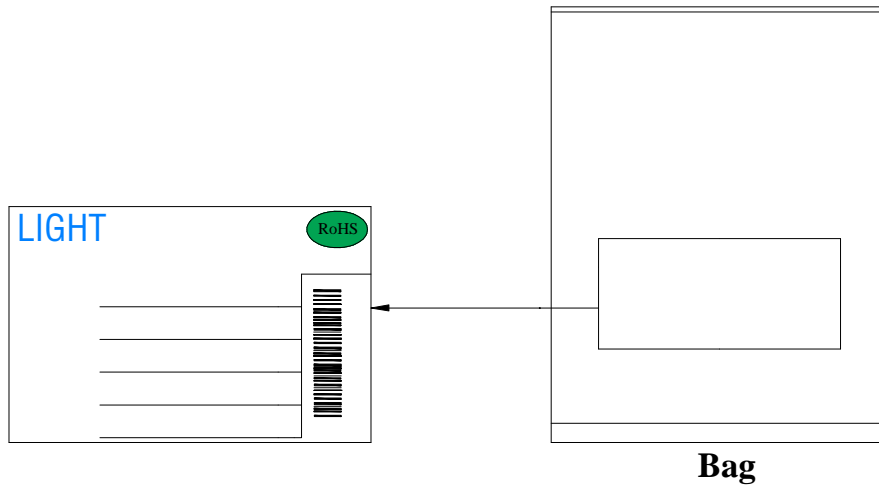


Fig. 4

PLACED

PACKAGE



| Bag minimum volume (pcs / Bag) | Bag volume (pcs / Bag) | Inner box volume (Bag / box) | Outer carton volume (Box / Carton) |
|-----------------------------------|---------------------------|---------------------------------|---------------------------------------|
| 500 | 1000 | 10 | 4 |